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Abraham et al.(10) **Pub. No.: US 2023/0230927 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **COMBINED BACKING PLATE AND
HOUSING FOR USE IN BUMP BONDED
CHIP ASSEMBLY**(71) Applicant: **International Business Machines
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Pleasantville, NY (US)(21) Appl. No.: **18/192,542**(22) Filed: **Mar. 29, 2023****Related U.S. Application Data**(63) Continuation of application No. 16/998,451, filed on
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ABSTRACT

A method for forming an electronic chip assembly. A first metal plate is coupled to a first side of a substrate to form a backing plate. A first cavity is created extending through the substrate to extend at least to the first metal plate. An electronic component is bonded to the substrate such that the electronic component is located within the first cavity. A second metal plate, having a second cavity, is disposed to a second side of the substrate, and over the first cavity such that the electronic component is encased within the first and second cavities by the first and second metal plates.

